

Redefining Performance Through System Balance

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Spring Processor Forum



2006

Talk Outline

- What drives our industry?
- Elements of Balanced System Performance
 - System-level bandwidth and power consumption
 - Single thread versus multi-thread performance
 - Understanding compatibility and transitions
 - Reliability
- AMD's Next Generation Processor Technology
 - Direct Connect Architecture enhancements
 - Core enhancements
- Crystal Ball: *New trends that may shape the future*
- Summary

Moore's Law (Gordon Moore, Electronics Magazine - April 1965)

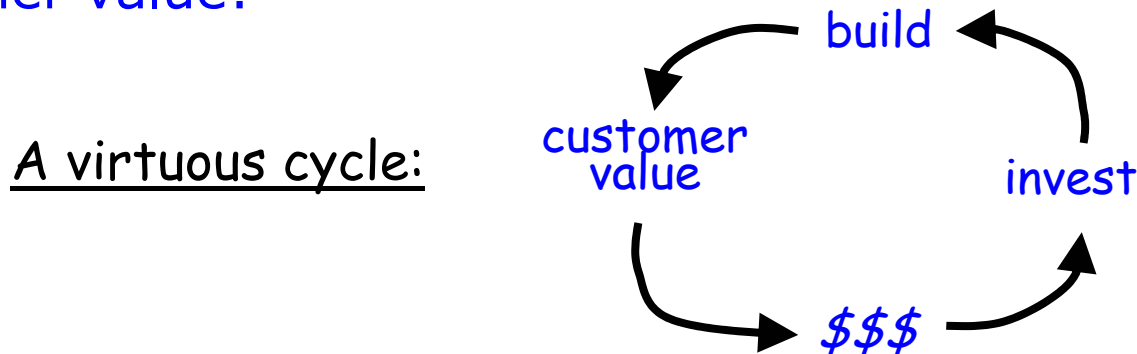
What he said:

- Double transistor integration every 18 months

Another trend often confused with Moore's Law:

- Double *performance* every 18 months
- This is actually an example of ongoing customer value

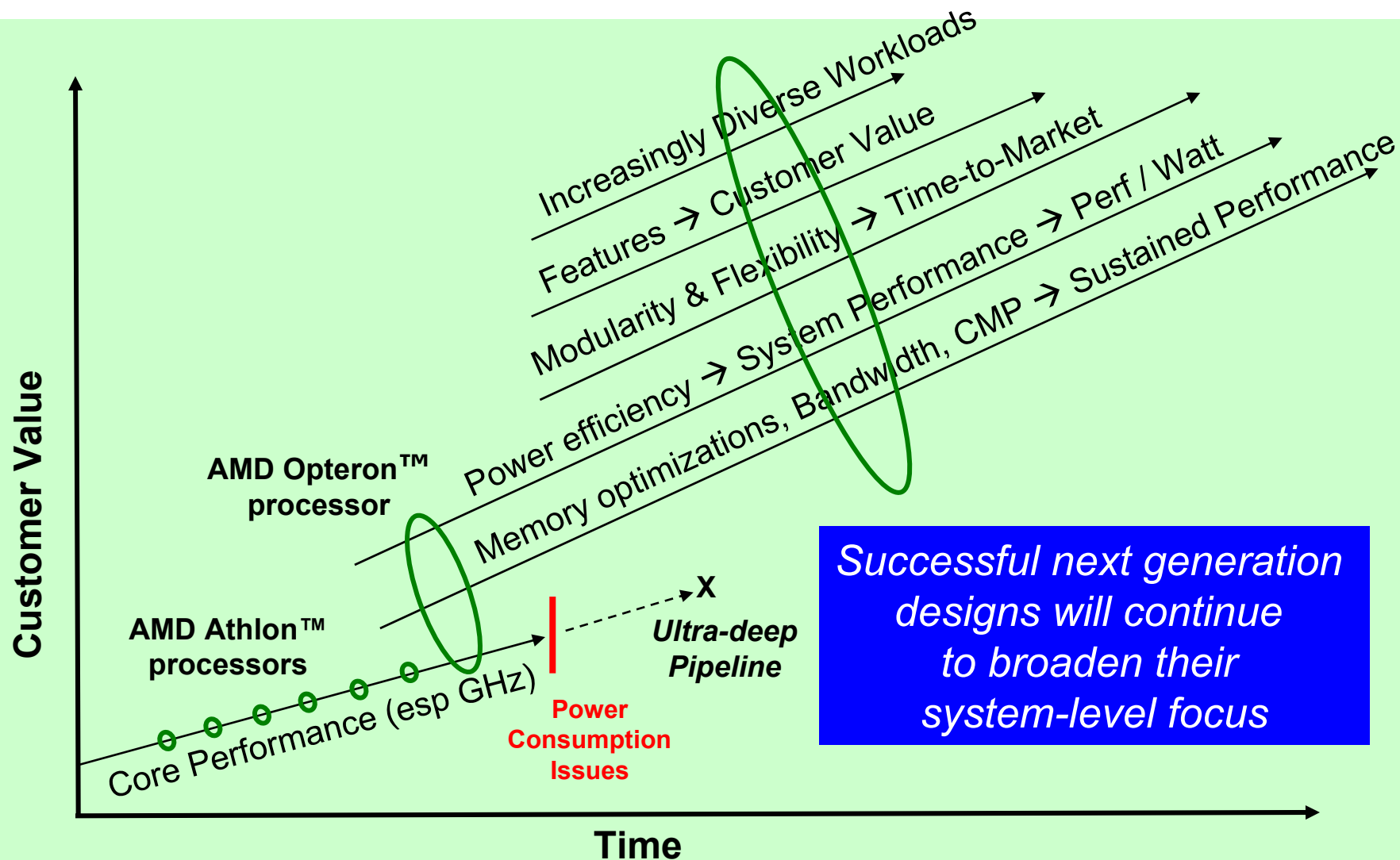
The semiconductor industry is dependent upon ongoing customer value:



The Question we should all be asking ourselves:

How do we continue increasing customer value?

Customer Value Trends



AMD is committed to understanding what customers *really* want



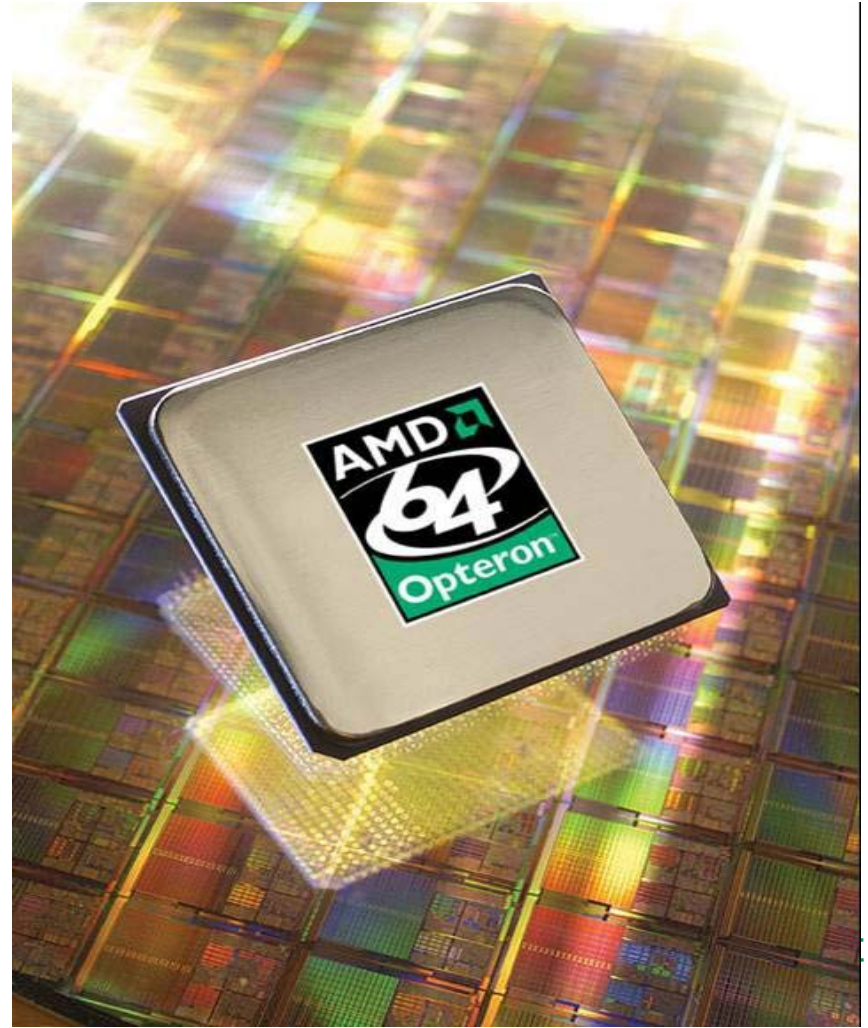
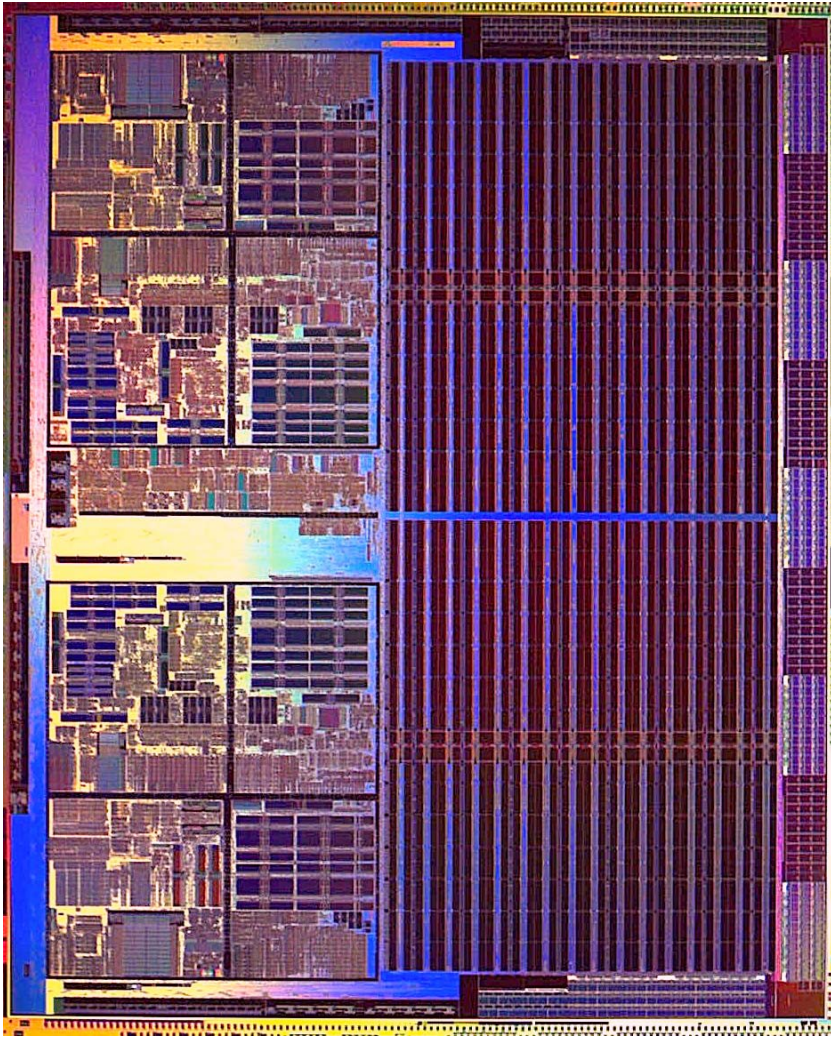
Expanding *connections* with customers, partners and end-users

Evolving beyond technologies and products to *solutions*

Enabling meaningful customer *differentiation* at ever declining costs

Customer-centric innovation

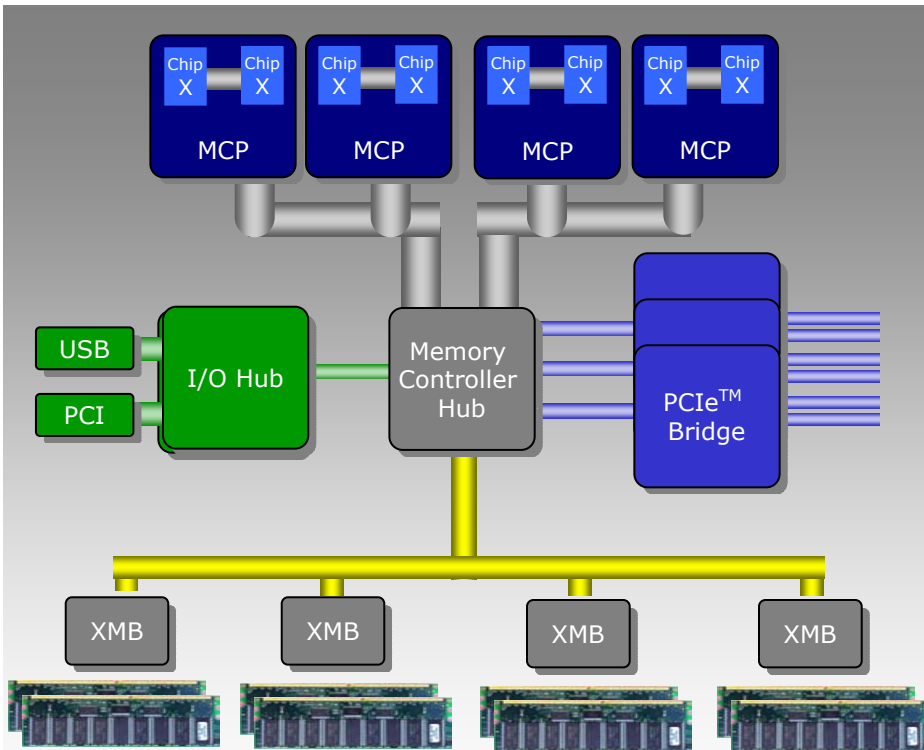
MPF 2004 - AMD Dual-Core Processor Chip



Talk Outline

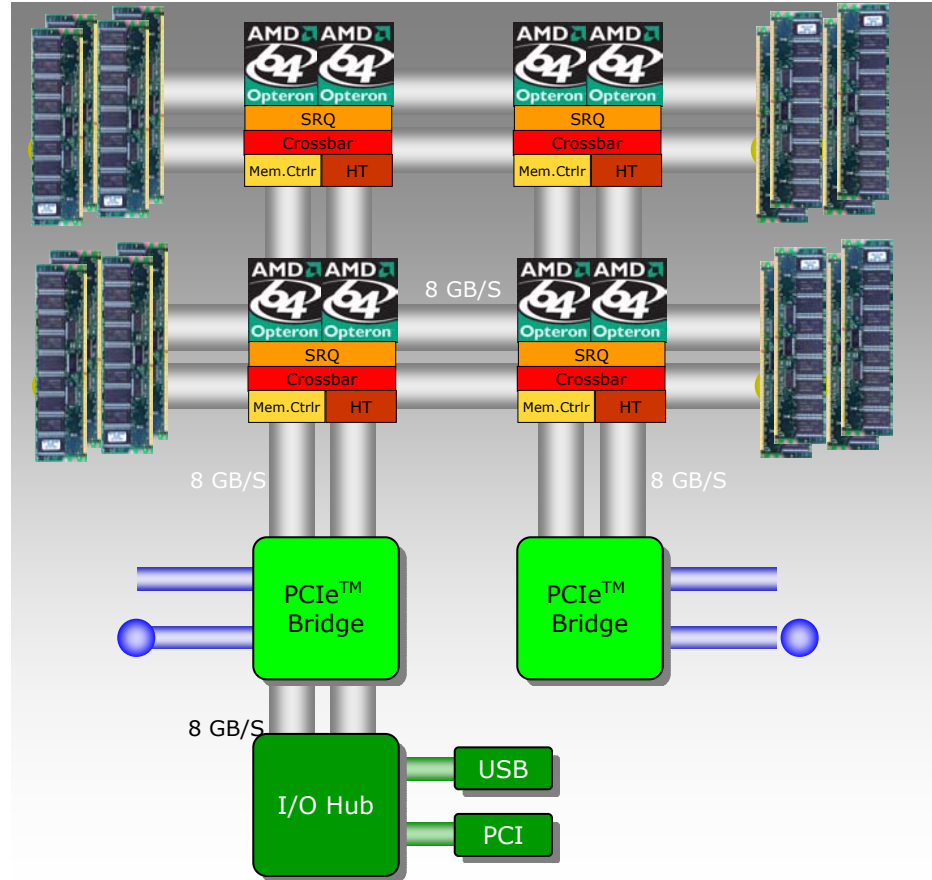
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Balanced Platform Bandwidth



Legacy x86 Architecture

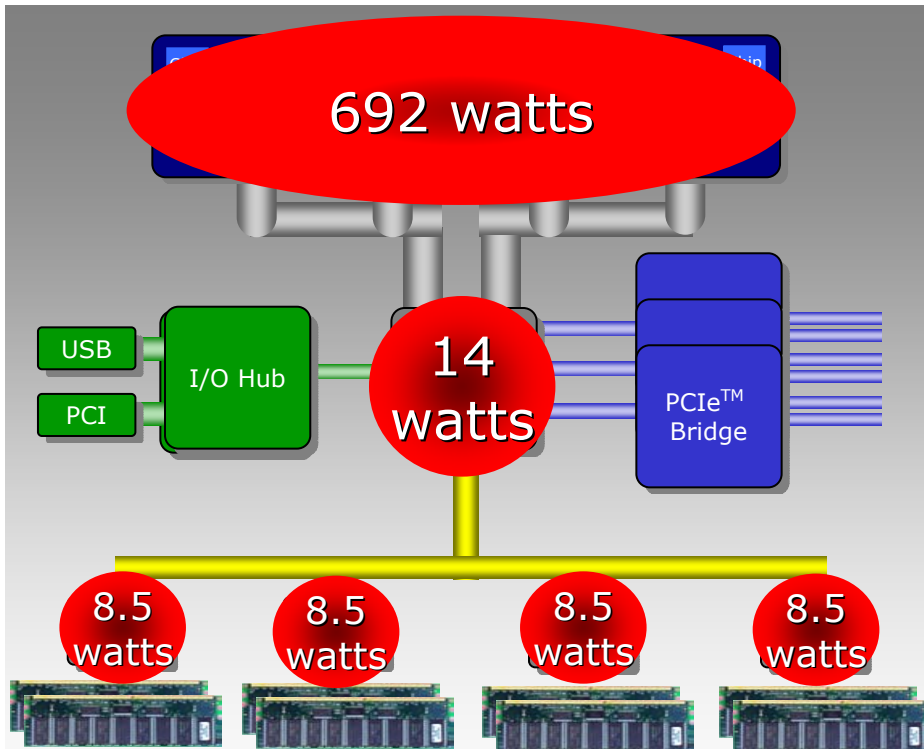
- 20-year old front-side bus (FSB) architecture
- CPUs, Memory, I/O all share a bus
- Major bottleneck to performance
- Faster CPUs or more cores \neq performance



AMD64's Direct Connect Architecture

- Industry-standard technology
- Direct Connect helps eliminate the FSB bottleneck
- HyperTransport™ interconnect offers scalable high bandwidth and low latency

System-level Power Consumption – Present Day

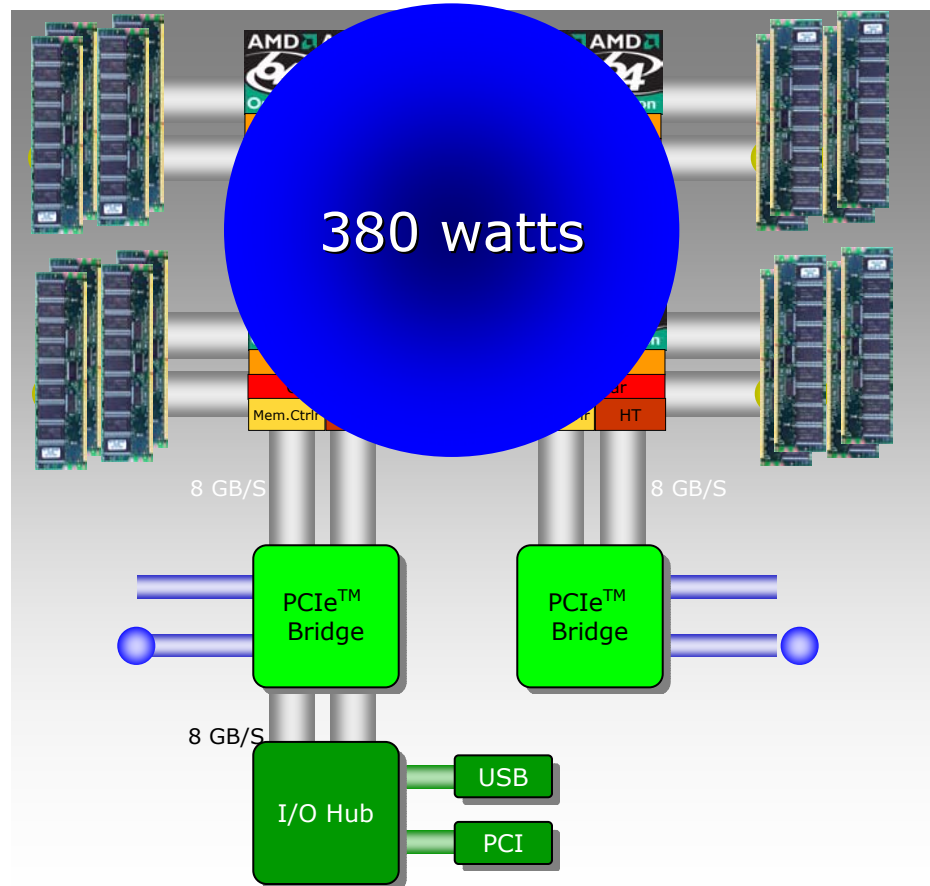


Dual-Core Packages with legacy technology

- 692 watts for processors (173w each)
- 48 watts for external memory controller

95% More Power

740 watts



Dual-Core AMD Opteron™ processors

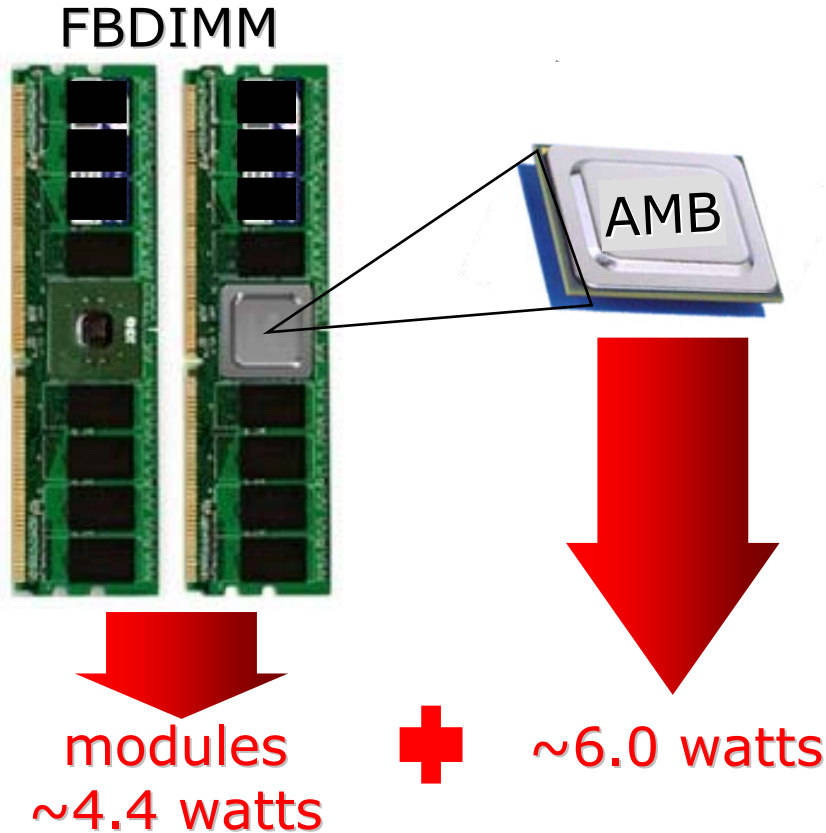
- 380 watts for processors (95w each)
- Integrated memory controllers

380 watts

Source: Mixture of publicly available data sheets and AMD internal estimates.
Actual system power measurements may vary based on configuration and components used



Taking a look at FBDIMM - Effects on Power



FBDIMM = ~10.4 watts each

Pro's

- Increased Memory Capacity

Cons

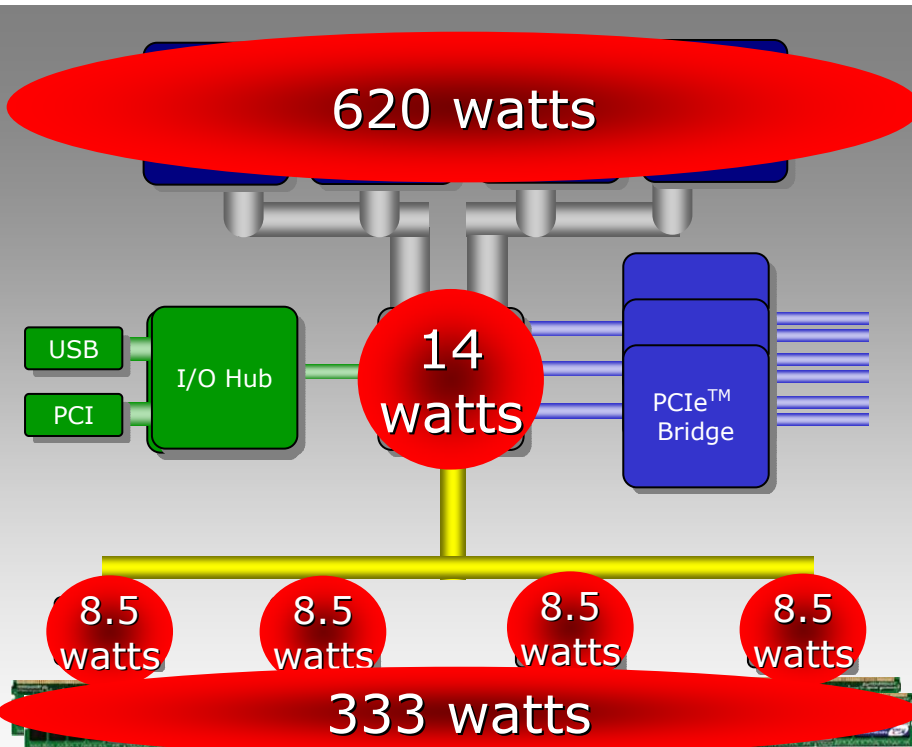
- More Latency
- Increased Power

Example:

32 FBDIMM modules = ~333 watts

32 DDR2 modules = ~140 watts

System-level Power Consumption (Plan) – Soon

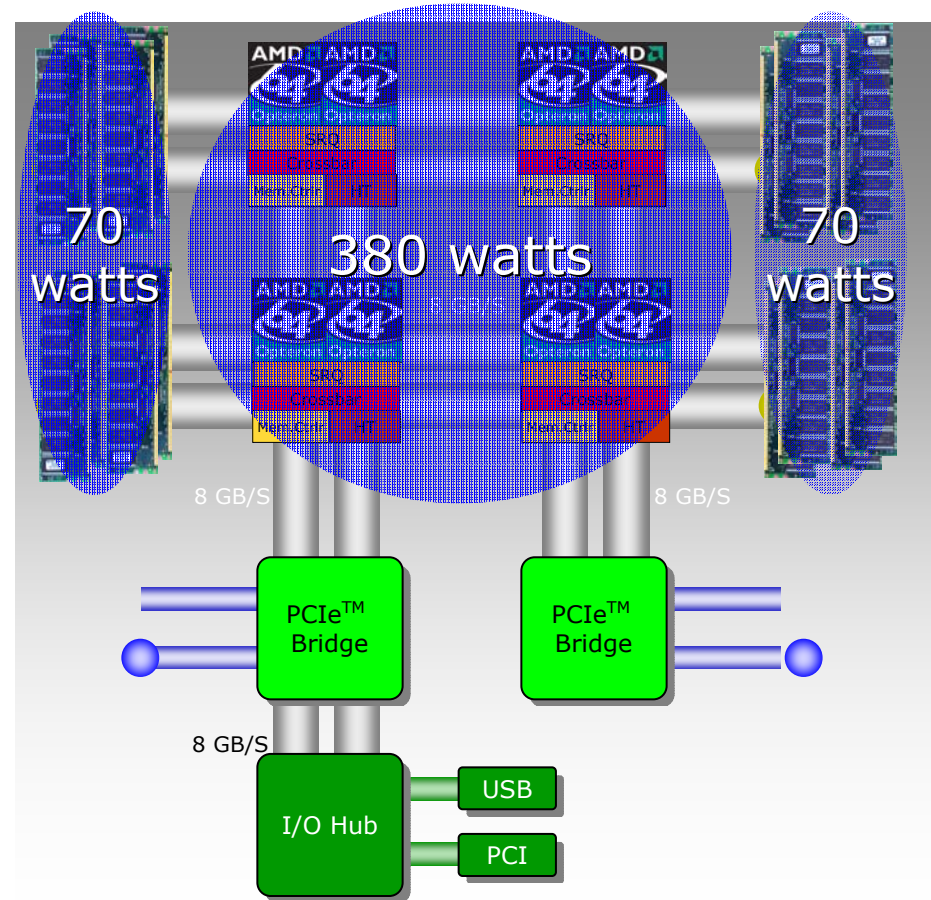


Legacy Dual-Core Chips in FBD Platform

- 620 watts for processors (155w each)
- 48 watts for external memory controller
- 333 watts for FBDIMM

93% More Power

1001 watts



Dual-Core AMD Opteron™ processors

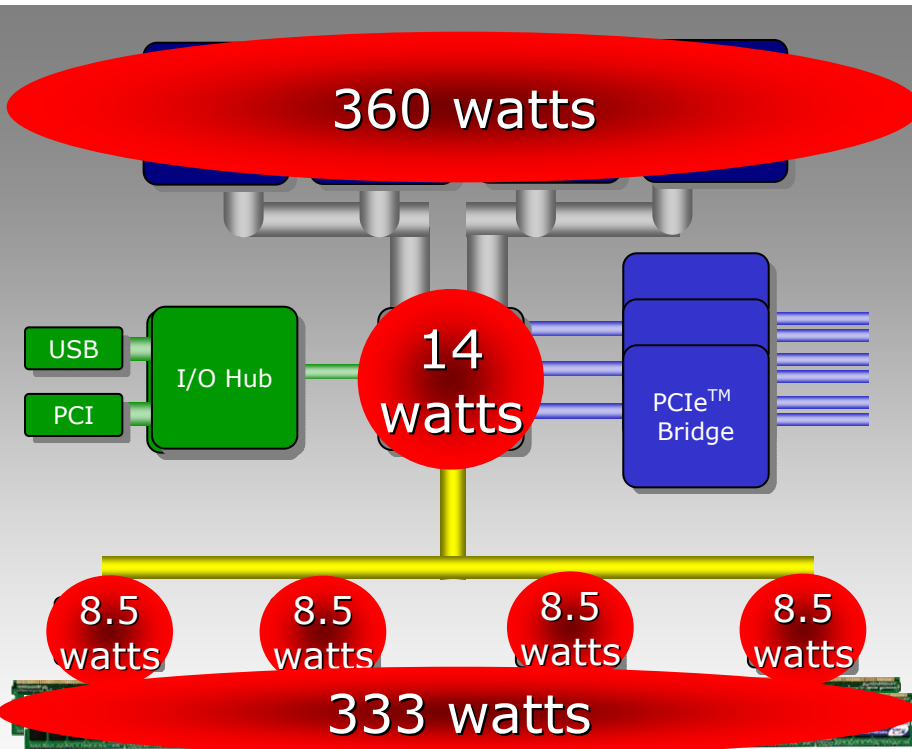
- 380 watts for processors (95w each)
- Integrated memory controllers
- 140 watts for DDR2

520 watts

Source: Mixture of publicly available data sheets and AMD internal estimates.
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System-level Power Consumption (Plan) – Later in 2006

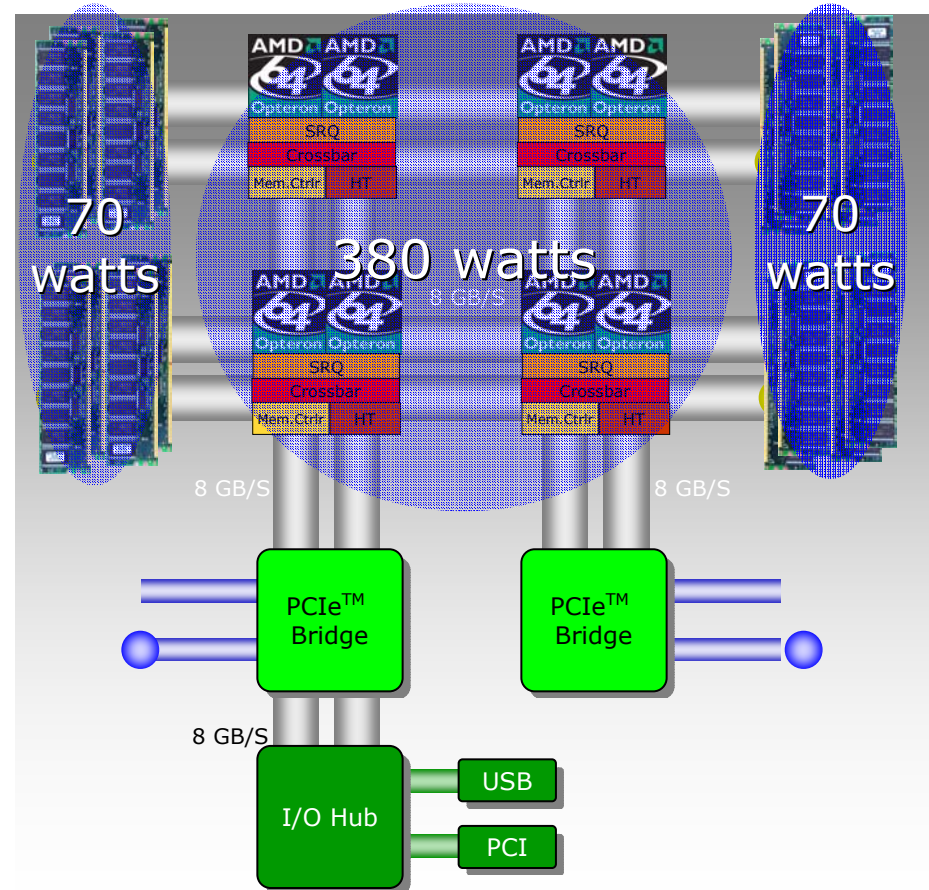


Improved Dual-Core Chips in FBD Platform

- 360 watts for processors (90w each)
- 48 watts for external memory controller
- 333 watts for FBDIMM

43% More Power

741 watts



Dual-Core AMD Opteron™ processors

- 380 watts for processors (95w each)
- Integrated memory controllers
- 140 watts for DDR2

520 watts

Source: Mixture of publicly available data and AMD internal estimates.
Actual system power measurements may vary based on configuration and components used

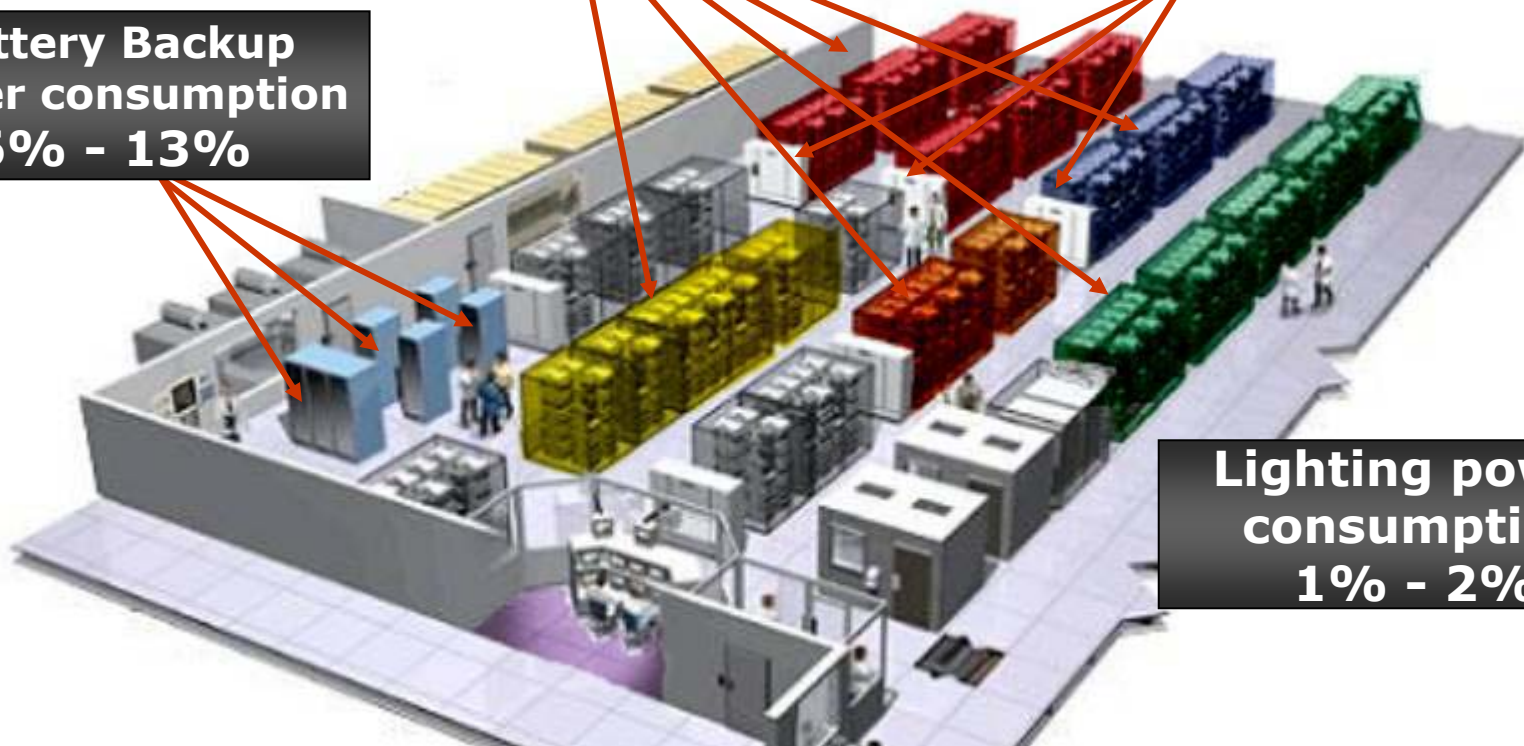


What's Consuming all the Power?

**Server power
consumption
38% - 63%**

**Computer Room Air
Conditioner power
consumption
23% - 54%**

**Battery Backup
power consumption
6% - 13%**



**Lighting power
consumption
1% - 2%**

**Server Power Consumption Impacts Power
throughout the Datacenter**

Reducing Power and Cooling Requirements with Processor Performance States

P-State

P0
2600MHz
1.40V
~95watts

P1
2400MHz
1.35V
~90watts

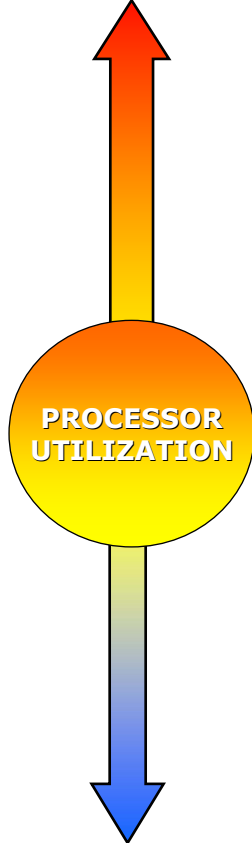
P2
2200MHz
1.30V
~76watts

P3
2000MHz
1.25V
~65watts

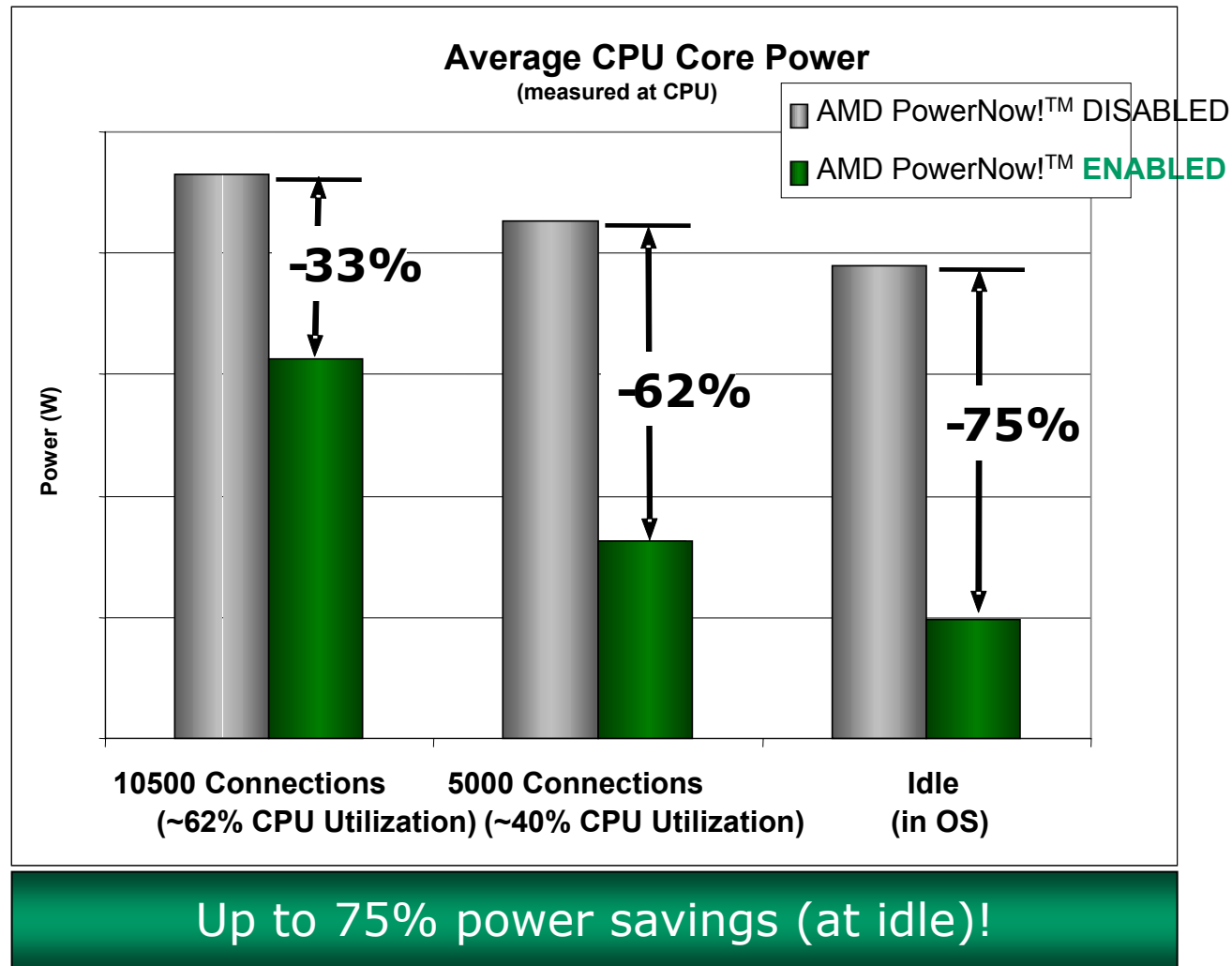
P4
1800MHz
1.20V
~55watts

P5
1000MHz
1.10V
~32watts

HIGH



LOW



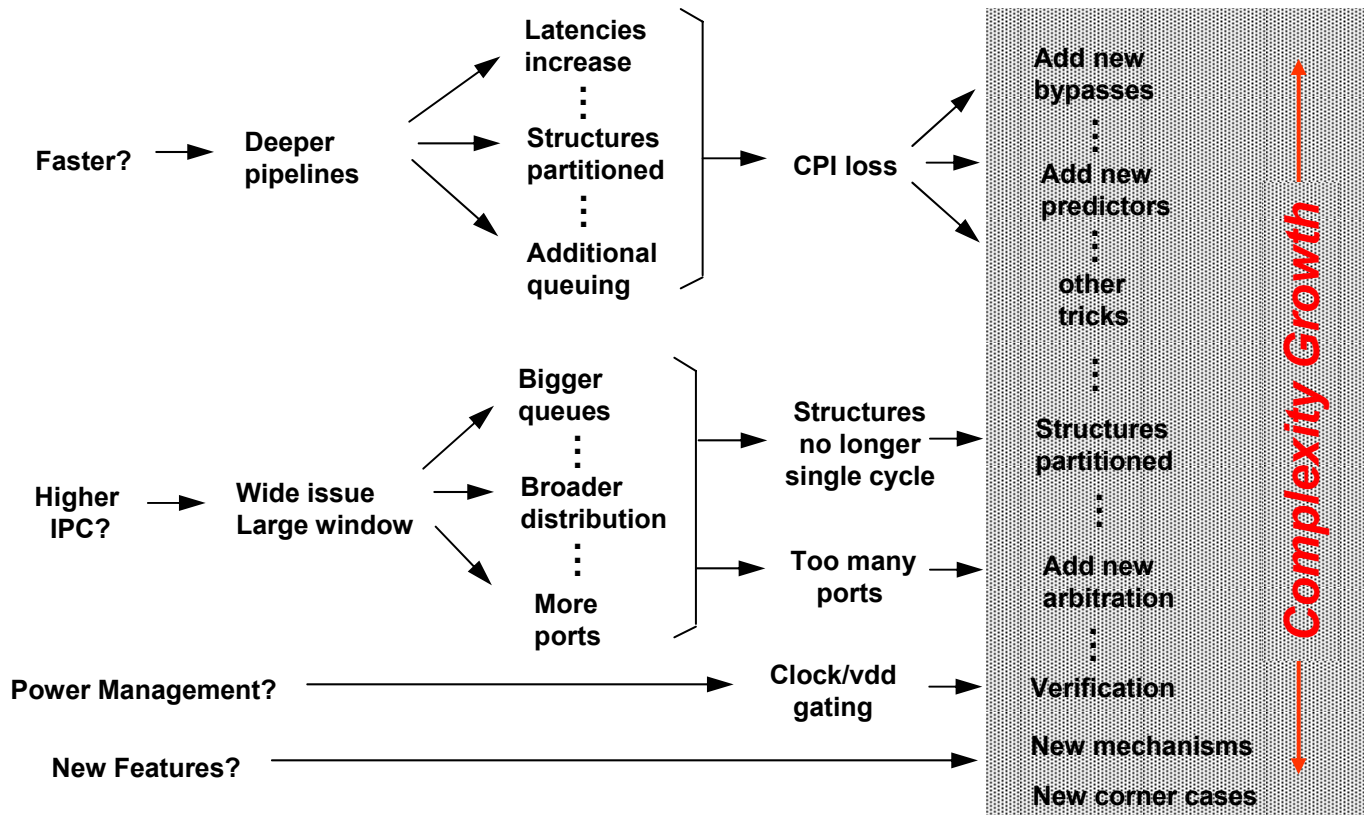
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A Closer Look at *Parallelism*

Instruction-level Parallelism (ILP)

- Executing multiple instructions from same program at the same time
- Superscalar hardware picks up most available ILP (*complexity effective*)



Superposition ...
complexity tends
to compound!

A Closer Look at *Parallelism*

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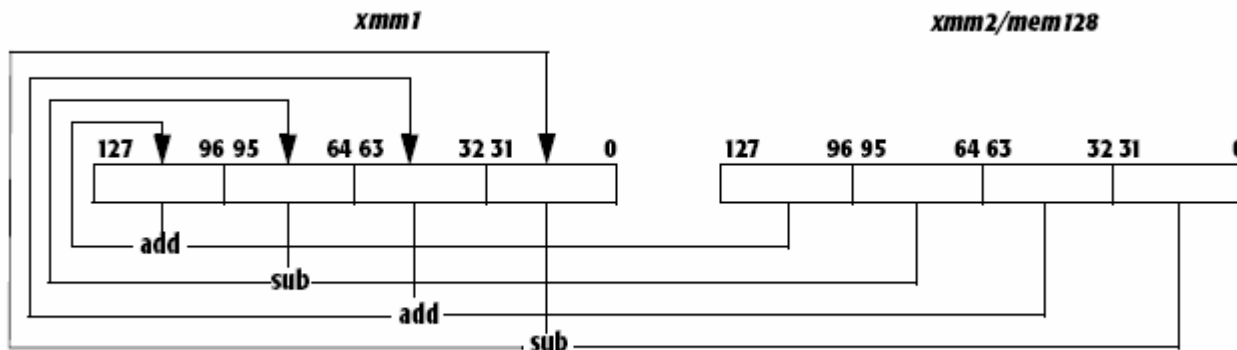
- Executing multiple instructions from same program at the same time
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Data-level Parallelism (DLP)

- Executing same instruction on multiple pieces of data at the same time
- Vector-style processing -- SSE hardware operates in this manner

ADDSUBPS

Add and Subtract Packed Single-Precision



A Closer Look at *Parallelism*

Instruction-level Parallelism (ILP)

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Data-level Parallelism (DLP)

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Thread-level Parallelism (TLP) – several types:

1. Concurrent Applications

- Multiple programs running at the same time
- Multiple OS's on virtualized hardware image
- Collection of services integrated into a single “application”

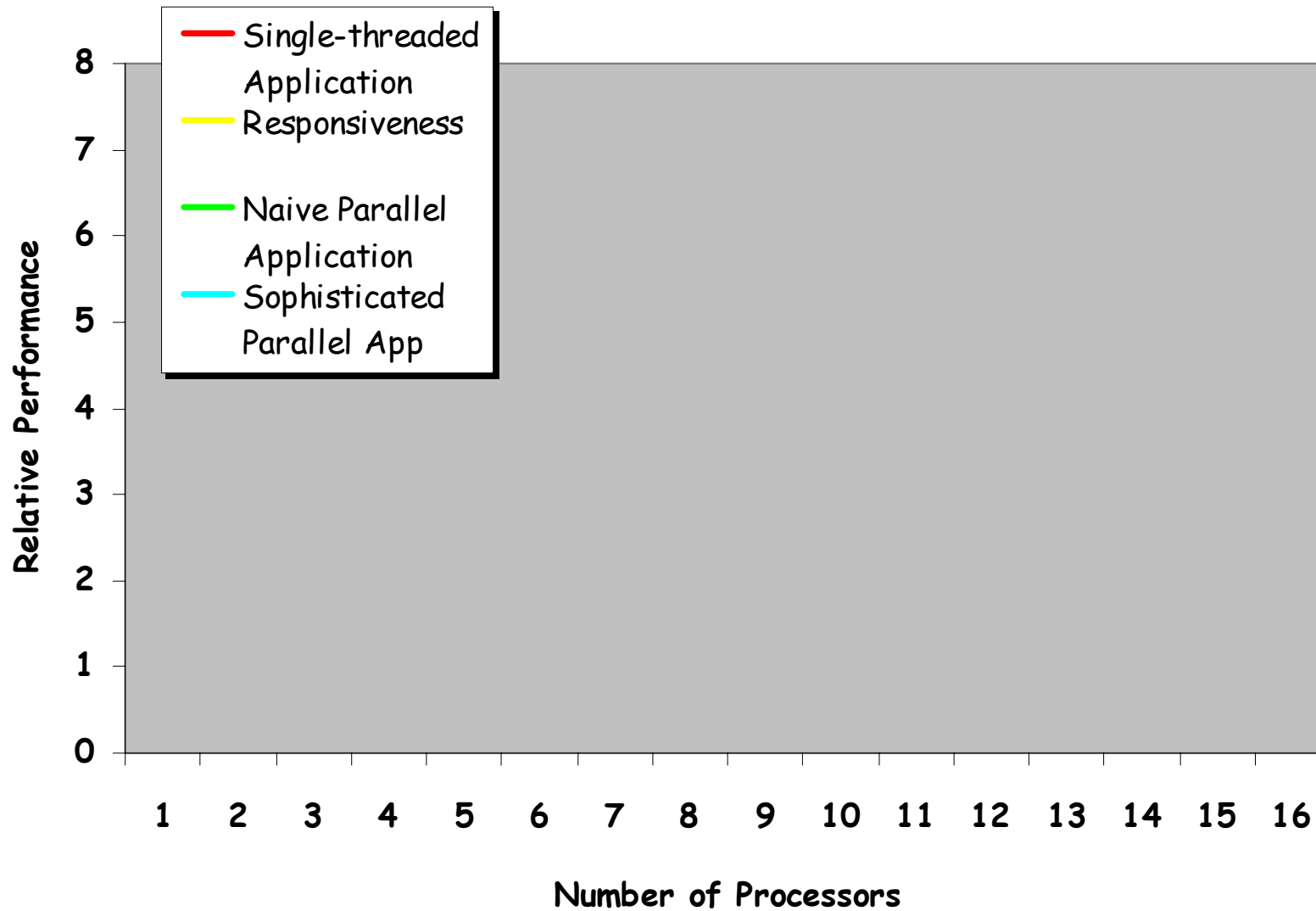
2. Internet Transactional

- Multiple computers running the same application

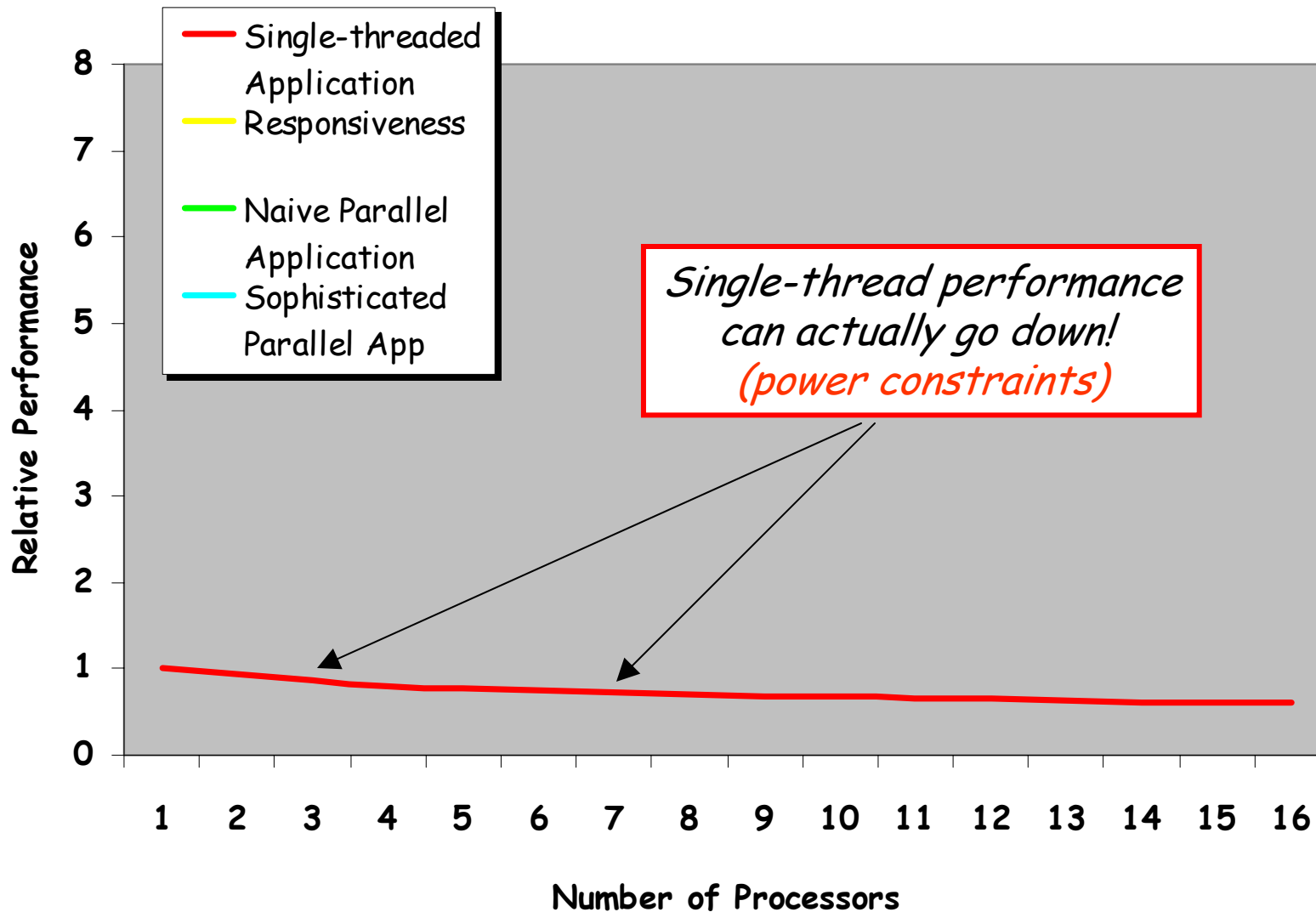
3. Parallel Applications - *The holy grail of computer science*

- Single application partitioned to run as multiple threads

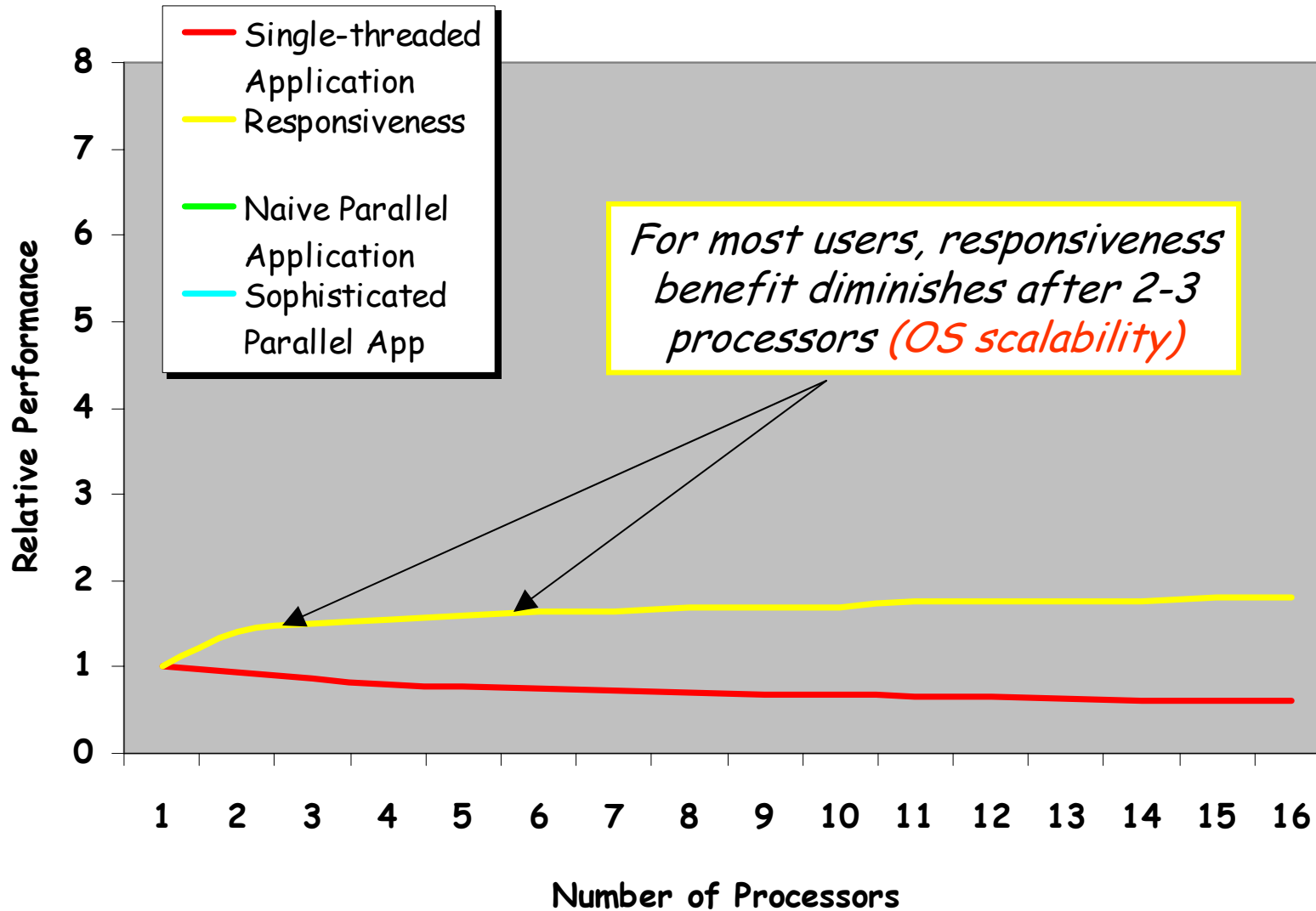
CMP Performance *(Theoretical values)*



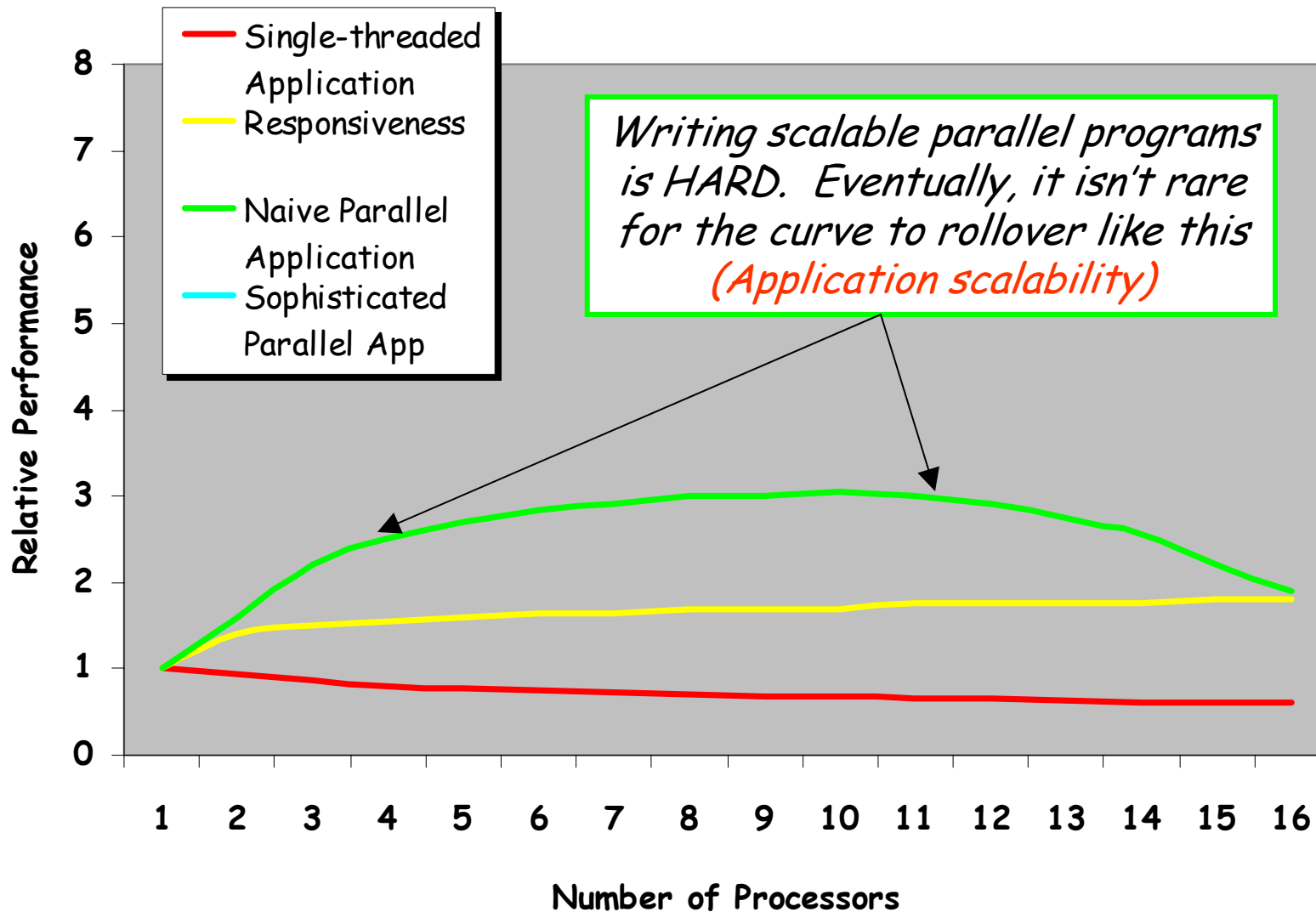
CMP Performance *(Theoretical values)*



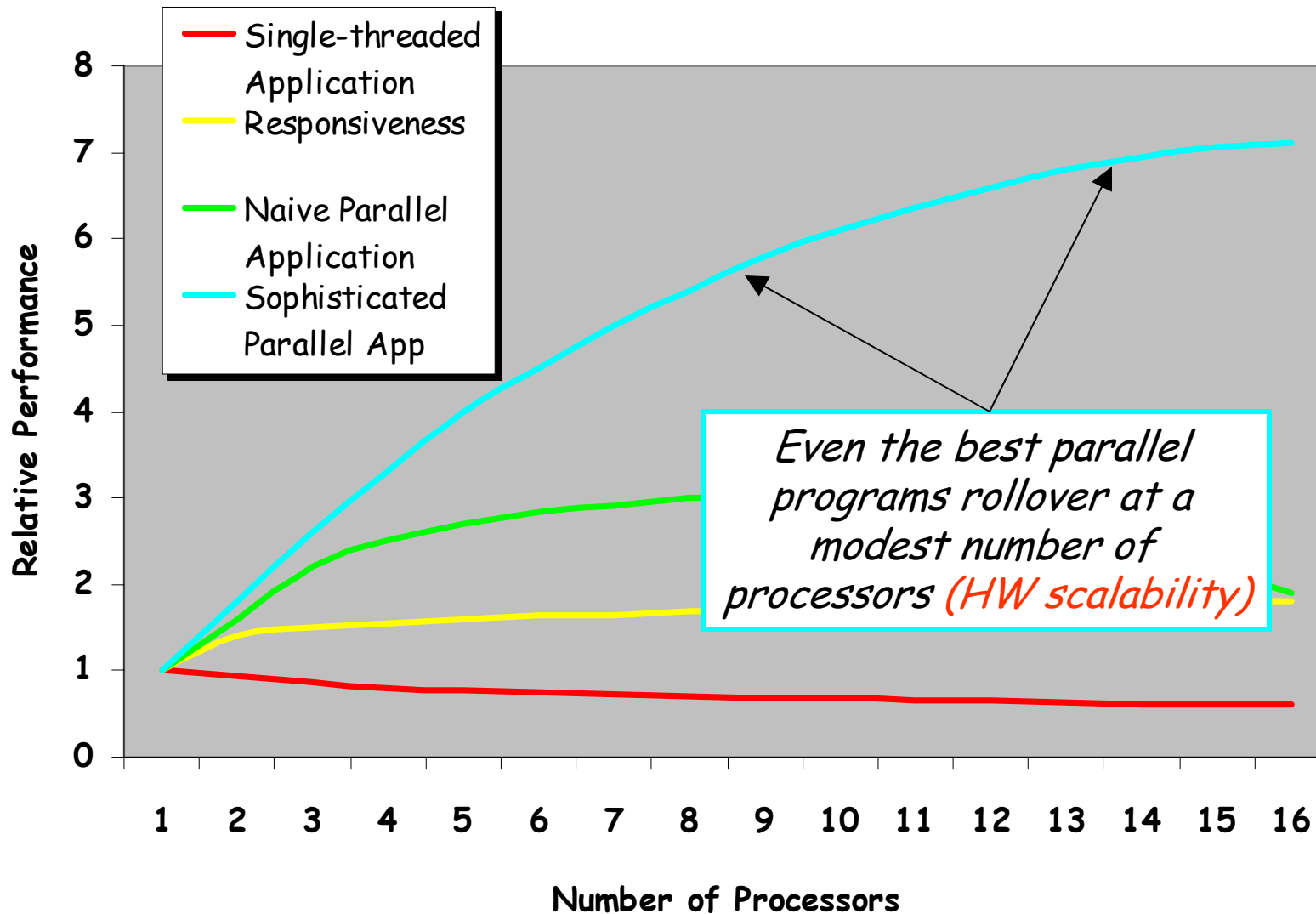
CMP Performance *(Theoretical values)*



CMP Performance *(Theoretical values)*



CMP Performance *(Theoretical values)*



The Transition to Parallel Applications

Single-threaded Applications

- Most of today's applications
- Well understood optimization techniques
- Advanced development, analysis and debug tools
- Conceptually, easy to think about

Parallel Applications

- Small number of applications (worked by experts for 10+ yrs)
- Awkward development, analysis and debug environments
- Parallel programming is hard!
- Amdahl's law is still a law...
- SW productivity is already in a crisis → ***this worsens things!***

Establishing an appropriate balance is key for managing this important transition

Understanding Compatibility and Transitions

- The compatibility requirement takes many forms:

- ☐ ISA compatibility (x86)
- ☐ Structural compatibility (single-thread programs)
- ☐ Socket compatibility (upgradeable systems)



- Will this ever change?

- ☐ Much slower than what some people want you to believe
- ☐ x86 acceptance has eclipsed most RISC architectures
- ☐ Our history shows:
 - ▶ *Viable products don't bet on wildly incompatible solutions*
 - ▶ *Actual results dominated by weakest link in the HW/SW symbiotic relationship*

- Eventually, higher-level abstractions will take over

- ☐ Maturing of software architectures and *layers*
- ☐ Waste some performance to enable more interoperability
- ☐ More on this later in the talk ...

Ideas unlikely to work



Sudden
turns



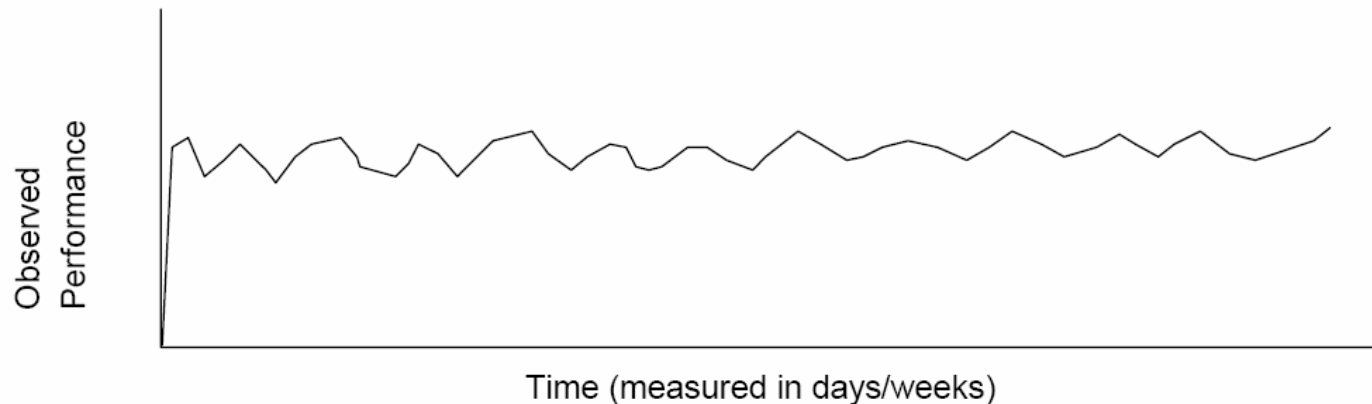
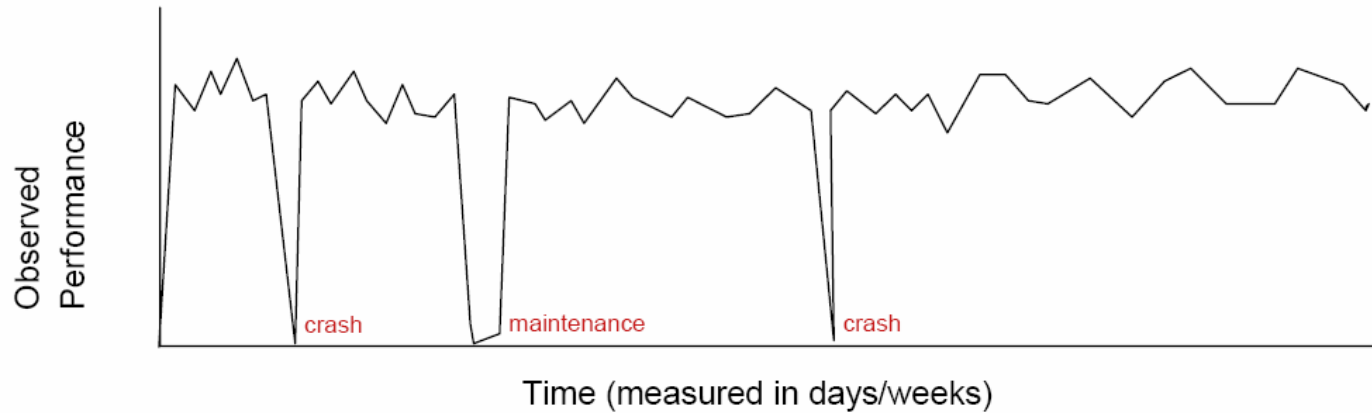
The fleet
approach

Forced
turns



Reliability and Robustness

Q: Which system has better performance?









For many customers, this is more important than raw performance

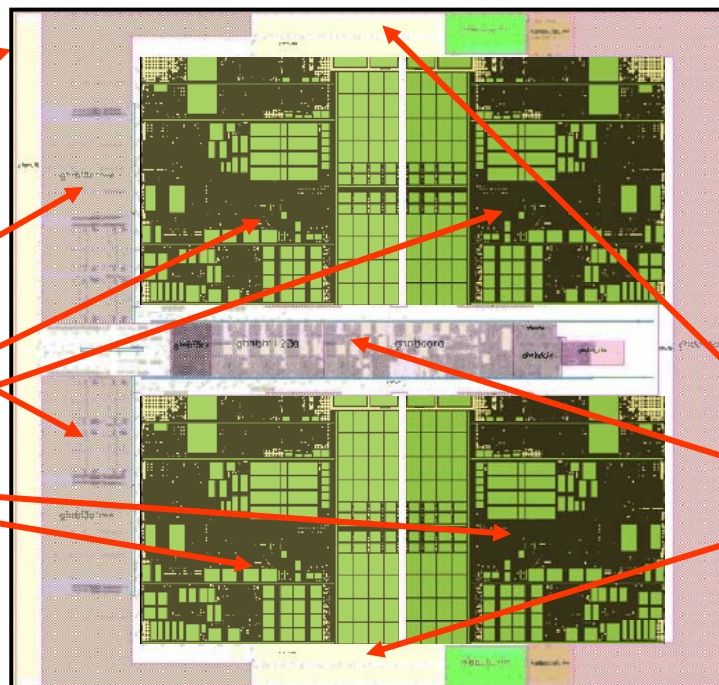
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AMD's Next Generation Processor Technology

- Scalable performance and balance  Fast HyperTransport™ links (up to 5.2 GT/sec)
Additional bandwidth enhancements
On-chip shared L3 cache
- Maintain performance per watt leadership  Independent NB and CPU power management
Independent CPU P-state and C-state controls
- Performance on diverse workloads  Enhanced IPC CPU core; >2X FPU performance
48-bit virtual and physical address space
1GB large page support
Platform support for co-processors
- Compatibility  DDR2 memory support with migration to DDR3
FBDIMM Gen1 and Gen2 at the *appropriate time*
HyperTransport™-1 backwards compatibility
- Enhanced Virtualization  I/O Virtualization
Nested paging support
- Enhanced RAS  Memory mirroring
Data poisoning support
HyperTransport™ retry protocol support

AMD's Next Generation Processor Technology



Native quad core die

Expandable shared
L3 cache

IPC enhanced
CPU cores

- ▶ 32B instruction fetch
- ▶ Improved branch prediction
- ▶ Out-of-order load execution
- ▶ Up to 4 DP FLOPS/cycle
- ▶ Dual 128-bit SSE dataflow
- ▶ Dual 128-bit loads per cycle
- ▶ Bit Manipulation extensions (LZCNT/POPCNT)
- ▶ SSE extensions (EXTRQ/INSERTQ, MOVNTSD/MOVNTSS)

Optimized for 65nm SOI
and beyond

Enhanced Direct
Connect Architecture
and Northbridge

- ▶ HyperTransport™ links (5.2GT/sec)
- ▶ Enhanced crossbar
- ▶ DDR2 with migration path to DDR3
- ▶ FBDIMM *when appropriate*
- ▶ Enhanced power management and RAS

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1. Co-processors and Accelerators



► Excellent way to get power-efficient performance boosts

- ❑ Special-purpose, tuned solutions for common functions
- ❑ Drop to low-power states when not in use
- ❑ Enabled by Modern API's

► Aligns with modularity imperative

- ❑ Co-processor becomes another (optional) "IP block"
- ❑ Micro-architecture: *Command delivery, Synchronization, Streaming*

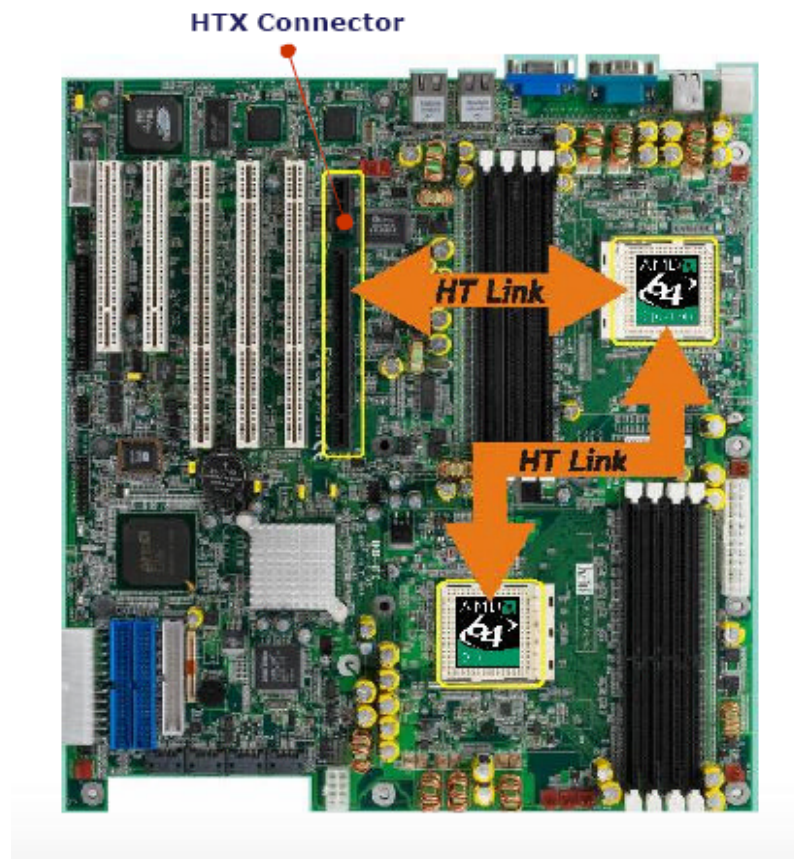
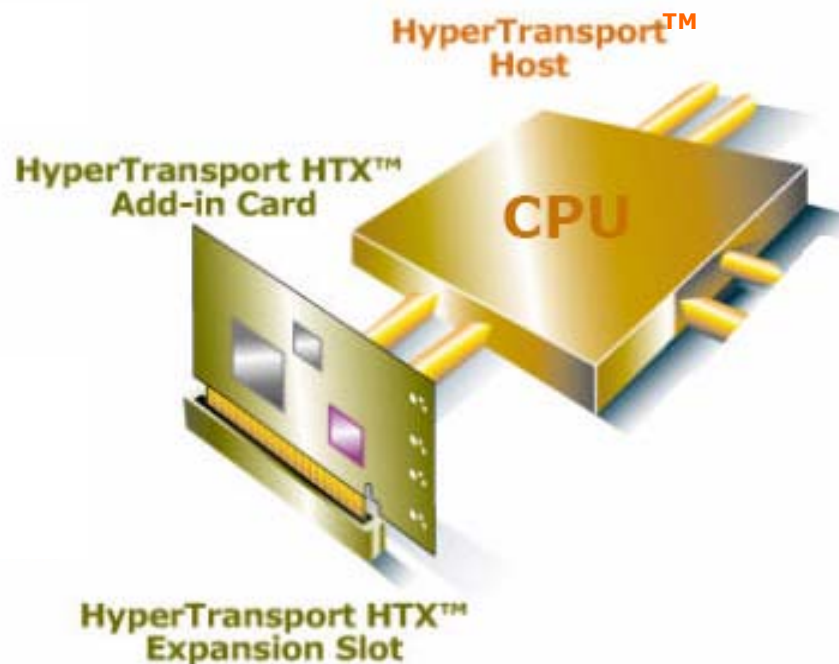
► Many possible opportunities now, and/or in the future

- ❑ Media processing
- ❑ JVM/CLR runtime hosting
- ❑ NIC integration (TOE, XML, SSL, etc)

Promising Concept



HyperTransport™ HTX™ Interface Enables System-level Coprocessing Today



2. Chip Multiprocessor (CMP) Generations

❖ Generation-0

- *Hasty integration of a bunch of cores*
- *Jam multiple single core devices into the same package*

❖ Generation-1

- Design from the **system-level inward**
- Balanced integration of cores and system functionality
- Address **HW scalability** inhibitors

❖ Generation-2

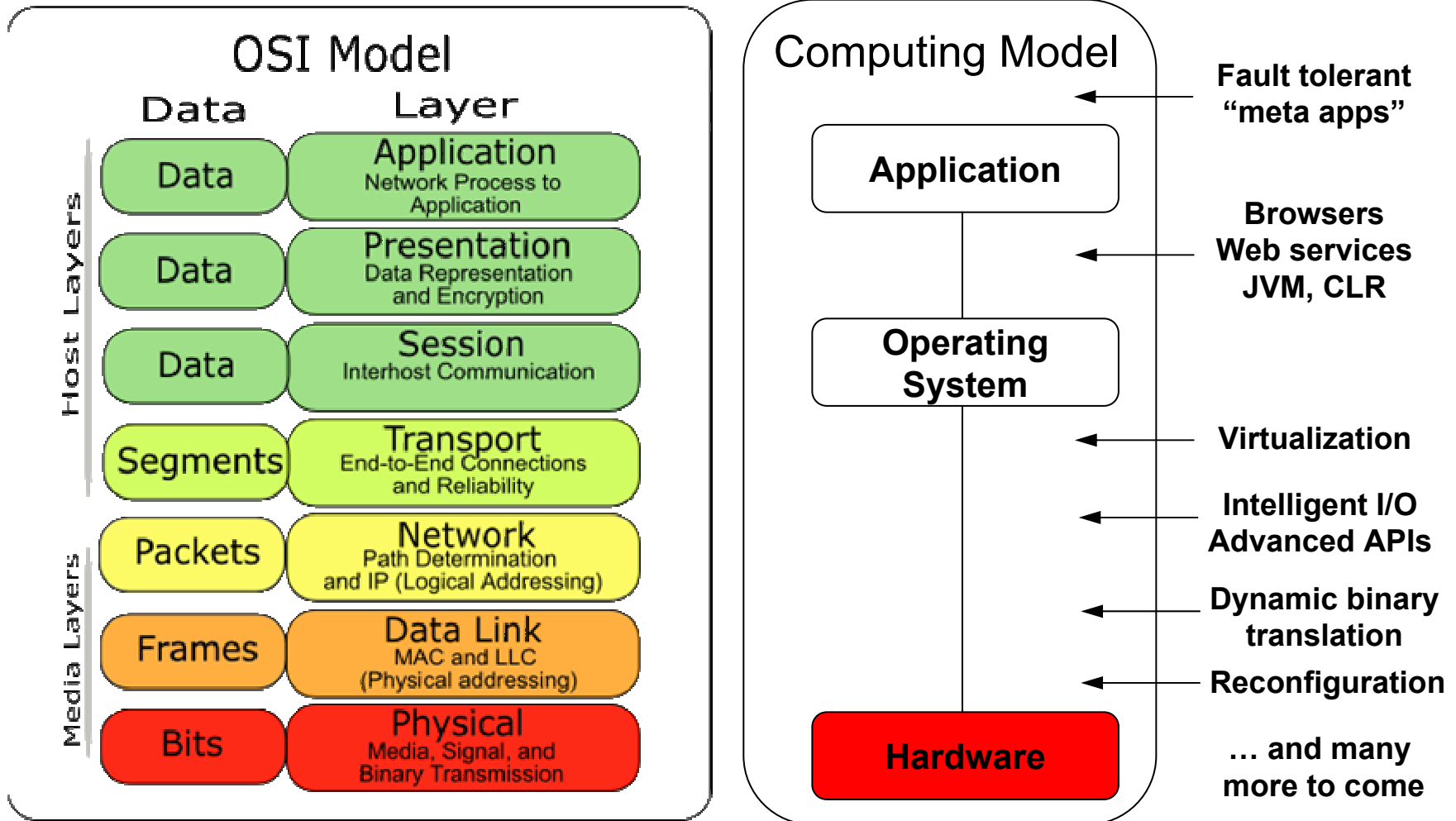
- Understand and address **interference** issues (*destructive & constructive*)
- **Chip-level framework** & infrastructure to support range of CMP variants
- Improve **SW visibility** & **optimization** for parallel application development

❖ Generation-3

- Introspective self-management
- Runtime adaptive flexibility
 - Specialized resources and optimizations*
 - Engage resources appropriate for each application*

3. The role of abstraction the next phase of computing

Remember this?



Foreshadows a HUGE paradigm shift !



Summary

- ✓ The semiconductor industry is driven by economics
 - Moore's Law is a key enabler in this cycle
 - But, underlying all of this is *customer value*
 - Today, customer value goes way beyond just performance
- ✓ AMD is focused on **customer-centric innovation** and **value**
 - System-level balance and power efficiency
 - Appropriate balance of single-thread performance and throughput
- ✓ AMD is investing heavily in extending our leadership
 - Next generation CPU technology
 - Next generation Direct Connect Architecture technology
 - Developing a fundamental understanding of important emerging trends

Enjoy the conference !



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